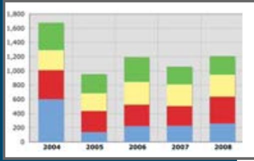
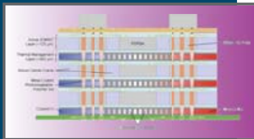
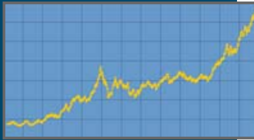
Advanced Packaging Update:

Market and Technology Trends

Vol. 4, 2007



Volume 4 of the Advanced Packaging Update for 2007 features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe substrates. Unit growth projections are also provided for stacked die CSP and package-on-package (PoP) shipments. A market growth analysis based on input from both captive and merchant assembly operations is provided. Key applications and drivers for unit volume and revenue growth are highlighted. New package developments include embedded ESD protection from Shocking Technologies and SCI-Sanmina Corporation.

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